RELIABILITY REPORT

FOR

MAX6575LZUT+

PLASTIC ENCAPSULATED DEVICES

September 16, 2013

MAXIM INTEGRATED

160 RIO ROBLES

SAN JOSE, CA 95134

Approved by
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Quality Assurance
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Conclusion

The MAX6575LZUT+ successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX6575L/H is a low-cost, low-current temperature sensor with a single-wire digital interface. It features accuracy of ±3°C at +25°C, ±4.5°C at +85°C, and ±5°C at +125°C. The MAX6575L/H is a monostable, externally triggered temperature sensor that allows a microprocessor (µP) to interface with up to eight temperature sensors using a single control line. Temperatures are sensed by measuring the time delay between the falling edge of the external triggering pulse and the falling edge of the subsequent pulse delays reported from the devices. Different sensors on the same I/O line use different timeout multipliers to avoid overlapping signals. The MAX6575L/H features eight different timeout multipliers; these are selectable by using the two time-select pins on each device and choosing the "L" or "H" version. The "L" version provides four delay ranges less than 50ms. The "H" version provides four delay ranges greater than 50ms. The MAX6575L/H is available in a space-saving 6-pin SOT23 package.

II. Manufacturing Information

A. Description/Function:	SOT Temperature Sensor with Multidrop Single Wire Digital Interface
B. Process:	S12
C. Number of Device Transistors:	302
D. Fabrication Location:	Oregon, California or Texas
E. Assembly Location:	Malasysia, Philippines, or Thailand
F. Date of Initial Production:	April 24, 1999

III. Packaging Information

A. Package Type:	6-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1601-0067
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	N/A
K. Single Layer Theta Jc:	N/A
L. Multi Layer Theta Ja:	230°C/W
M. Multi Layer Theta Jc:	76°C/W

IV. Die Information

A. Dimensions:	57X35 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Richard Aburano (Manager, Reliability Engineering) Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 80 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 13.7 \times 10^{-9}$

$\lambda = 13.7$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maximintegrated.com/qa/reliability/monitor. Cumulative monitor data for the S12 Process results in a FIT Rate of 0.02 @ 25C and 0.33 @ 55C (0.8 eV, 60% UCL).

B. E.S.D. and Latch-Up Testing (ESD lot I4CAAQ001J D/C 9914, Latch-up lot N4CABA004D D/C 0414)

The MS14 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX6575LZUT+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80	0	I4CAAQ001D, D/C 9913

Note 1: Life Test Data may represent plastic DIP qualification lots.